

### **Abstract of the Disclosure**

What is proposed here is a method of structuring surfaces of glass-type materials and variants of this method, comprising the following steps of operation: providing a semiconductor substrate, structuring, with the formation of recesses, of at least one surface of the semiconductor substrate, providing a substrate of glass-type material, joining the semiconductor substrate to the glass-type substrate, with a structured surface of the semiconductor substrate being joined to a surface of the glass-type substrate in an at least partly overlapping relationship, and heating the substrates so bonded by annealing in a way so as to induce an inflow of the glass-type material into the recesses of the structured surface of the semiconductor substrate. The variants of the method are particularly well suitable for the manufacture of micro-optical lenses and micro-mechanical components such as micro-relays or micro-valves.

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